

## PATENT ASSIGNMENT COVER SHEET

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Assignment ID: PATI373321

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
<b>Name</b>		<b>Execution Date</b>
INDUSTRY ACADEMY COOPERATION FOUNDATION OF SEJONG UNIVERSTY		06/05/2024
<b>RECEIVING PARTY DATA</b>		
<b>Company Name:</b>	KONINKLIJKE PHILIPS N.V.	
<b>Street Address:</b>	HIGH TECH CAMPUS 52	
<b>City:</b>	EINDHOVEN	
<b>State/Country:</b>	NETHERLANDS	
<b>Postal Code:</b>	5656 AG	
<b>PROPERTY NUMBERS Total: 5</b>		
<b>Property Type</b>	<b>Number</b>	
<b>Application Number:</b>	16642414	
<b>Application Number:</b>	17681879	
<b>Application Number:</b>	18416906	
<b>Application Number:</b>	17285336	
<b>Application Number:</b>	18191375	
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
<b>Phone:</b>	2033515705	
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<b>ATTORNEY DOCKET NUMBER:</b>	2023PJT01897	
<b>NAME OF SUBMITTER:</b>	Patti DeMichele	
<b>SIGNATURE:</b>	Patti DeMichele	
<b>DATE SIGNED:</b>	07/19/2024	
<b>Total Attachments: 2</b>		

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**PATENT**

**REEL: 068030 FRAME: 0720**

## Deed of Assignment

This Deed of Assignment (the “Deed of Assignment”) is made between Industry Academy Cooperation Foundation of Sejong University, a Korean entity, having its registered office at 216, Jiphyun Bldg., 209, Neungdong-ro, Gwangjin-gu, Seoul, Republic of Korea (“Assignor”) and Koninklijke Philips N.V., a corporation organised and existing under the laws of the Netherlands, having its registered office at High Tech Campus 52, 5656 AG Eindhoven, The Netherlands (“Assignee”).

WHEREAS, Assignor possesses a legal interest in: (1) patents and patent applications; (2) any and all continuation, divisional, renewal, substitute, re-examination or reissue applications of the patents and patent applications; and (3) all rights of priority, as listed in Annex 1 (collectively: “the Patents”);

WHEREAS, Assignor and Assignee entered into a Patent Assignment Agreement dated 30 May 2024 (“the Agreement”);

WHEREAS, the parties wish to confirm that through the Agreement Assignee acquired the entire right, title and interest in and to said Patents effective as of 30 May 2024;


WHEREAS, it is desired that the assignment of the Patents be made a matter of record in the appropriate patent offices; and

NOW THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, Assignor hereby confirms the sale, assignment and transfer to Assignee of all Assignor’s worldwide right, title, and interest in and to the Patents, to be held and enjoyed by Assignee, for its own use and benefit, and by Assignee’s successors and confirms the assignment for their own use and benefit, for the full duration of the terms for which Patents may be granted in any country, subject to the terms and conditions of the Agreement.

Assignor hereby grants full power of attorney to Assignee to submit solely this Deed of Assignment, including the Annex, to the patent authorities of Republic of Korea, the United States, China and India, and to request those authorities to record the assignment of the legal title to the Assigned Patents from Assignor to Assignee in the appropriate registers.

IN WITNESS WHEREOF, Assignor executes this Assignment and is made effective as of the date below. The person who signs this Assignment below represents that such person is fully authorised to sign the Assignment on behalf of Assignor.

**Industry Academy Cooperation Foundation of  
Sejong University**

Signature:   
Name: Sang-Ho Yoo  
Title: President  
Date: 5 June 2024

**Annex**

Philips' reference	Jurisd.	Title	Patent Appl. No.	Patent No.
2017P02865WOUS	US	Method for constructing tile structure and apparatus therefor	16/642,414	11297317
2017P02865US	US	Method for constructing tile structure and apparatus therefor	17/681,879	11917149
2017P02865US01	US	Method for constructing tile structure and apparatus therefor	18/416,906	
2018P01216WOUS	US	Video encoding/decoding method and device	17/285,336	11659163
2018P01216US	US	Video encoding/decoding method and device	18/191,375	